



# **RFBPF Series – 2520(1008) - RoHS Compliance**

## MULTILAYER CERAMIC BAND PASS FILTER

## Halogens Free Product

## 2.4 GHz ISM Band Working Frequency

# P/N: RFBPF2520070AMT

\*Contents in this sheet are subject to change without prior notice.

## **Approval sheet**

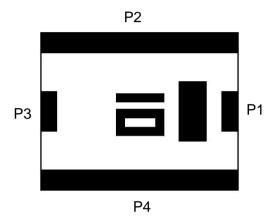
- 1. Multilayer LTCC ( Low Temperature Cofired Ceramics ) Technology
- 2. Reflow solderable
- 3. Miniatured Size  $2.5 \times 2.0 \times 0.7 \text{ mm}^3$
- 4. Low Insertion Loss
- 5. High attenuation on 2<sup>nd</sup> and 3<sup>rd</sup> harmonic suppressed
- 6. Suitable for 2.45 GHz Working Frequency Operation

## APPLICATIONS

- 1. 2.4GHz ISM Band RF Application
- 2. Bluetooth, Wireless LAN, HomeRF

## CONSTRUCTION

Top view



PIN	Definition			
P1	Input			
P2	2 GND			
P3	Output			
P4	GND			

#### DIMENSIONS

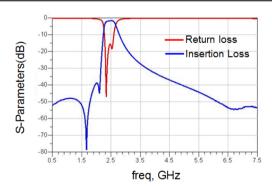
Figure	Symbol	Dimension (mm)
Bottom view	L	2.50 ± 0.20
	W	2.00 ± 0.20
	Т	0.70 ± 0.10
	A	0.20 ± 0.20
	В	0.55 ± 0.20
	С	0.50 ± 0.20
Side view	D	0.25 ± 0.20
	E	0.20 ± 0.20



## **ELECTRICAL CHARACTERISTICS**

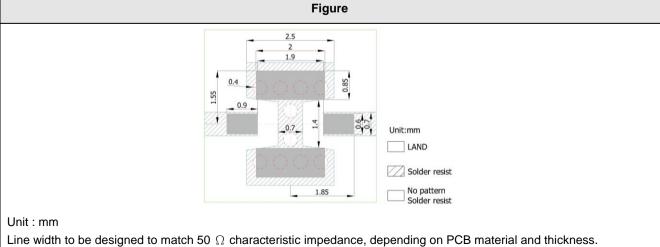
RFBPF2520070AMT	Specification
Frequency range	2400 ~ 2500 MHz
Incention Land	2.0 dB at 25°C
Insertion Loss	2.2dB at -40 ~ +85°C
	45 dB min. @ 824 ~ 849MHz
	45 dB min. @ 869 ~ 880MHz
	45 dB min. @ 925 ~ 960MHz
	45 dB min. @ 1570 ~ 1580MHz
	45 dB min. @ 1710 ~ 1785MHz
	40 dB min. @ 1805 ~ 1850MHz
Attenuation	35 dB min.@ 1850 ~ 1910MHz
	35 dB min. @ 1920 ~ 1990MHz
	25 dB min. @ 2110 ~ 2170MHz
	5 dB min. @ 2750 ~ 3000MHz
	15 dB min. @ 3000 ~ 4800 MHz
	30 dB min. @ 4800 ~ 5000 MHz
	30 dB min.@ 5150 ~ 5850MHz
	20 dB min. @7200 ~ 7500 MHz
VSWR	2.0 max.
Impedance	50 Ω
Operation Temperature Range	-40°C ~ +85°C
Moisture sensitivity levels	MSL is LEVEL 1 (Refer to : IPC/JEDEC J-STD-020)

## **Typical Electrical Chart**



## SOLDER LAND PATTERN







## Approval sheet

RELIABILITY TEST		
Test item	Test condition / Test method	Specification
Solderability	*Solder bath temperature $: 235 \pm 5^{\circ}$ C	At least 95% of a surface of each terminal
JIS C 0050-4.6	*Immersion time $: 2 \pm 0.5$ sec	electrode must be covered by fresh solder.
JESD22-B102D	Solder:Sn3Ag0.5Cu for lead-free	
Leaching	*Solder bath temperature $\div$ 260 $\pm$ 5°C	Loss of metallization on the edges of each
(Resistance to	*Leaching immersion time $\div$ 30 $\pm$ 0.5 sec	electrode shall not exceed 25%.
dissolution of	Solder : SN63A	
metallization)		
IEC 60068-2-58		
Resistance to soldering	*Preheating temperature : $120~150^{\circ}$ C,	No mechanical damage.
heat	1 minute.	
JIS C 0050-5.4		Electrical specification shall satisfy the
	*Solder temperature : 270±5°C	descriptions in electrical characteristics under
	*Immersion time : 10±1 sec	the operational temperature range within -40 $\sim$
		85°C.
	Solder : Sn3Ag0.5Cu for lead-free	Loss of metallization on the edges of each
	Measurement to be made after keeping at	electrode shall not exceed 25%.
	room temperature for 24±2 hrs	
Desa Test		
Drop Test JIS C 0044	*Height : 75 cm	No mechanical damage.
Customer's specification.	*Test Surface : Rigid surface of concrete or	Electrical specification shall satisfy the
	steel.	descriptions in electrical characteristics under
	*Times : 6 surfaces for each units ; 2 times	the operational temperature range within -40 ~
	for each side.	85°C.
Vibration		
JIS C 0040	*Frequency : 10Hz~55Hz~10Hz(1min)	No mechanical damage.
	*Total amplitude : 1.5mm	Electrical specification shall satisfy the
	*Test times : 6hrs.(Two hrs each in three	descriptions in electrical characteristics under
	mutually perpendicular directions)	the operational temperature range within -40 ~
		85°C.
Adhesive Strength	*Pressurizing force :	No remarkable damage or removal of the
of Termination	5N(≦0603) ; 10N(>0603)	termination.
JIS C 0051- 7.4.3		
Bending test	*Test time : 10±1 sec	
Bending test	The middle part of substrate shall be	No mechanical damage.
JIS C 0051- 7.4.1	pressurized by means of the pressurizing rod	Electrical specification shall satisfy the
	at a rate of about 1 mm/s per second until the	descriptions in electrical characteristics under
	deflection becomes 1mm/s and then pressure	the operational temperature range within -40 $\sim$
	shall be maintained for $5\pm1$ sec.	85°C.
	Measurement to be made after keeping at	
	room temperature for 24±2 hours	



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Temperature cycle JIS C 0025	<ol> <li>30±3 minutes at -40°C±3°C,</li> <li>10~15 minutes at room temperature,</li> <li>30±3 minutes at +85°C±3°C,</li> <li>10~15 minutes at room temperature,</li> <li>Total 100 continuous cycles</li> <li>Measurement to be made after keeping at room temperature for 24±2 hrs</li> </ol>	No mechanical damage. Electrical specification shall satisfy the descriptions in electrical characteristics under the operational temperature range within -40 ~ 85°C.
High temperature JIS C 0021	*Temperature : 85°C±2°C *Test duration : 1000+24/-0 hours Measurement to be made after keeping at room temperature for 24±2 hrs	No mechanical damage. Electrical specification shall satisfy the descriptions in electrical characteristics under the operational temperature range within -40 ~ 85°C.
Humidity (steady conditions) JIS C 0022	<ul> <li>*Humidity : 90% to 95% R.H.</li> <li>*Temperature : 40±2°C</li> <li>*Time : 1000+24/-0 hrs.</li> <li>Measurement to be made after keeping at room temperature for 24±2 hrs</li> <li>% 500hrs measuring the first data then 1000hrs data</li> </ul>	No mechanical damage. Electrical specification shall satisfy the descriptions in electrical characteristics under the operational temperature range within -40 ~ 85°C.
Low temperature JIS C 0020	*Temperature : -40°C±2°C *Test duration : 1000+24/-0 hours Measurement to be made after keeping at room temperature for 24±2 hrs	No mechanical damage. Electrical specification shall satisfy the descriptions in electrical characteristics under the operational temperature range within -40 ~ 85°C.

Typical examples of soldering processes that provide reliable joints without any damage are given in Fig 2,

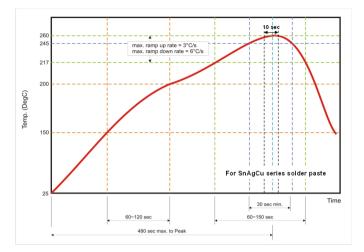


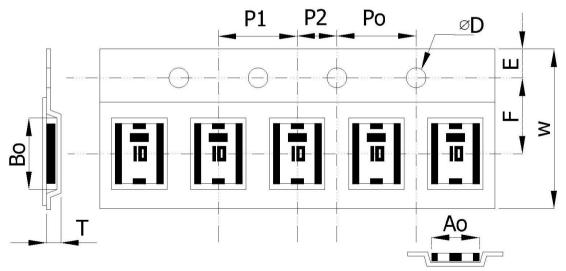
Fig 2. Infrared soldering profile

## ORDERING CODE

RF	BPF	252007	0	Α	м	Т
Walsin	Product Code	Dimension code	Unit of	Application	Specification	Packing
RF device	BPF :	Per 2 digits of	dimension	A : 2.4GHZ ISM	Design code	T : Reeled
	Band Pass Filter	Length, Width,	0 : 0.1 mm	Band		
		Thickness :	1 : 1.0 mm			
		e.g. :				
		252008 =				
		Length 25,				
		Width 20,				
		Thickness 7				

Minimum Ordering Quantity: 2000 pcs per reel.

## PACKAGING



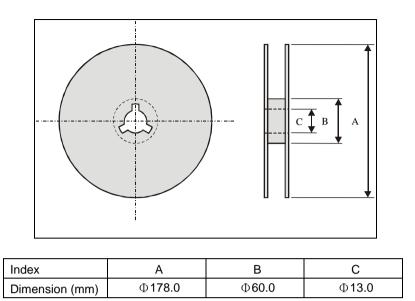
## Plastic Tape specifications (unit :mm)

Index	Ao	Во	ΦD	Т	W
Dimension (mm)	$\textbf{2.27} \pm \textbf{0.05}$	$\textbf{2.74} \pm \textbf{0.05}$	1.5± 0.1	$1.18{\pm}0.05$	$\textbf{8.00} \pm \textbf{0.10}$
Index	E	F	Po	P1	P2
Dimension (mm)	$1.75\pm0.10$	$\textbf{3.50} \pm \textbf{0.05}$	$4.00\pm010$	$4.00\pm0.10$	$2.00\pm0.05$

## ASC\_RFBPF2520070AMT\_V02

華新科技股份有限公司 Walsin Technology Corporation

## **Reel dimensions**



Taping Quantity:2000 pieces per 7" reel

### CAUTION OF HANDLING

#### Limitation of Applications

Please contact us before using our products for the applications listed below which require especially high reliability for the prevention of defects, which might directly cause damage to the third party's life, body or property.

- (1) Aircraft equipment
- (2) Aerospace equipment
- (3) Undersea equipment
- (4) Medical equipment
- (5) Disaster prevention / crime prevention equipment
- (6) Traffic signal equipment
- (7) Transportation equipment (vehicles, trains, ships, etc.)
- (8) Applications of similar complexity and /or reliability requirements to the applications listed in the above.

### Storage condition

- (1) Products should be used in 6 months from the day of WALSIN outgoing inspection, which can be confirmed.
- (2) Storage environment condition.
  - Products should be storage in the warehouse on the following conditions.
  - Temperature : -10 to +40°C
  - Humidity : 30 to 70% relative humidity
  - Don't keep products in corrosive gases such as sulfur. Chlorine gas or acid or it may cause oxidization of electrode, resulting in poor solderability.
  - Products should be storage on the palette for the prevention of the influence from humidity, dust and son on.
  - Products should be storage in the warehouse without heat shock, vibration, direct sunlight and so on.
  - Products should be storage under the airtight packaged condition.

>>Walsin Technology(华新科技)